

BONDING OF A MULTI-LAYER CIRCUIT TO A HEAT SINK

Abstract

A method for manufacturing a printed circuit bonded to a heat sink includes producing the printed circuit comprising at least one conductive layer circuit pattern laminated to at least one side of a dielectric layer; first adhering a first side of a bond film to the printed circuit, wherein the first adhering conforms the printed circuit to the bond film to substantially remove air entrapment between the printed circuit and the bond film; and second adhering a second side of the bond film to the heat sink, wherein the first adhering and the second adhering bond the heat sink to the printed circuit.

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